

Title (en)

METHOD AND DEVICE FOR ALIGNING A TEST SYSTEM AND AN ELECTRIC MEMBER TO BE TESTED

Title (de)

VERFAHREN UND VORRICHTUNG ZUR ANGLEICHUNG EINES TESTSYSTEMS UND EINES ZU TESTENDEN ELEKTRISCHEN GLIEDS

Title (fr)

PROCEDE ET DISPOSITIF D'ALIGNEMENT D'UN SYSTEME DE TEST AVEC UN ELEMENT ELECTRIQUE A TESTER

Publication

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Application

**EP 08737536 A 20080418**

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Abstract (en)

[origin: WO2008135821A1] The invention relates to a method for locating an electrically conductive member (5c) at the surface of a circuit (5), the method comprising the steps of: placing the circuit in a device for testing or measuring electrically conductive members, said device comprising at least one source (1a) of a light beam (2) and a control unit (CNTL) for applying the light beam to several impact points at the surface of the circuit; applying the light beam (2) to several impact points at the surface of the circuit (5) in order to generate at the surface of the circuit a particle flow having a detectable intensity depending on the nature of the material at the impact point of the light beam; comparing the intensity variations of the light beam generated at each impact point; and deriving the position of the conductive member at the surface of the circuit. The invention can be used for precisely locating a circuit in a test device using the photoelectric effect.

IPC 8 full level

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